

AP3765

Pin Configuration

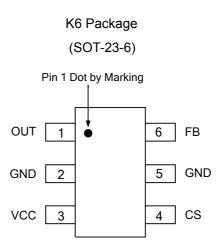


Figure 2. Pin Configuration of AP3765 (Top View)

Pin Description

Pin Number	Pin Name	Function		
1	OUT	This pin drives the base of external power NPN switch		
2, 5	GND	Ground		
3	VCC	Supply voltage		
4	CS	The primary current sense		
6	FB	The voltage feedback from the auxiliary winding		



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Functional Block Diagram

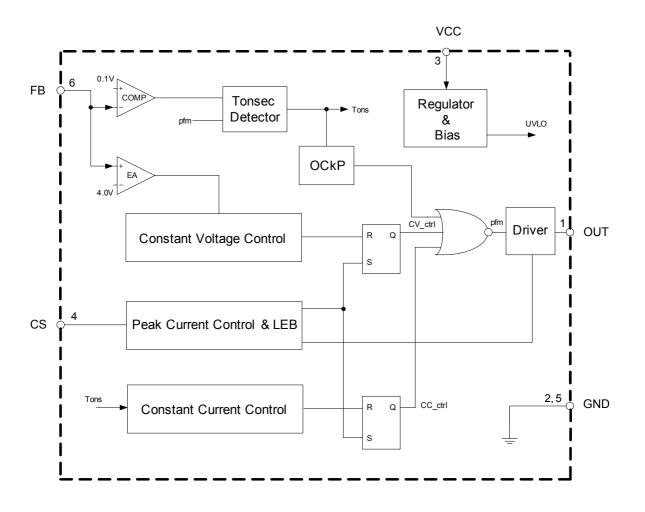
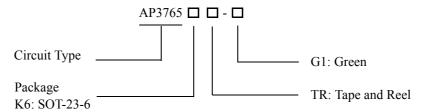


Figure 3. Functional Block Diagram of AP3765



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Ordering Information



Package	Temperature Range	Part Number	Marking ID	Packing Type	
SOT-23-6	-40 to 85°C	AP3765K6TR-G1	GBB	Tape & Reel	

BCD Semiconductor's products, as designated with "G1" suffix in the part number, are RoHS compliant and Green.

Absolute Maximum Ratings (Note 1)

Parameter	Value	Unit	
Supply Voltage VCC	-0.3 to 36	V	
Voltage at CS, OUT to GND	-0.3 to 7	V	
FB Input	-40 to 10	V	
Output Current at OUT	Internally limited	A	
Operating Junction Temperature	150	°C	
Storage Temperature	-65 to 150	°C	
Lead Temperature (Soldering, 10s)	300	°C	
Thermal Resistance Junction-to-Ambient	250	°C/W	
ESD (Machine Model)	200	V	
ESD (Human Body Model)	2000	V	

Note 1: Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "Recommended Operating Conditions" is not implied. Exposure to "Absolute Maximum Ratings" for extended periods may affect device reliability.

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BCD Semiconductor Manufacturing Limited



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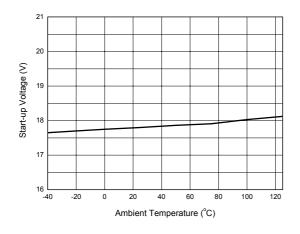
Electrical Characteristics

(V $_{CC}$ =15V, T $_{A}$ =25 o C, unless otherwise specified.)

Parameter		Symbol	Conditions	Min	Тур	Max	Unit
UVLO SECTION				•			•
Start-up Threshold		V _{TH (ST)}		16	18.5	21	V
Minimal Operating Voltage		V _{OPR} (min)		7.2	9	10.2	V
STANDBY CURRENT	SECTION	I		'	•		
Start-up Current		I_{ST}	$V_{CC} = V_{TH (ST)}$ -0.5V, Before start-up			0.6	μА
Operating Current		I _{CC(OPR)}	Static		200	320	μΑ
DRIVE OUTPUT SECT	ION			•			•
OUT Maximum Current	Sink	I _{OUT}		50			mA
OCT Mannam Carrent	Source		24	30	36		
CURRENT SENSE SEC	TION						
Current Sense Threshold		V _{CS}		455	510	545	mV
Pre-Current Sense		V _{CS(PRE)}		365	410	455	mV
Leading Edge Blanking					750		ns
FEEDBACK INPUT SE	CTION			•			
Feedback Pin Input Current	Leakage	I_{FB}	V _{FB} =4V	2.0	2.5	3.1	μА
Feedback Threshold		V_{FB}		3.89	3.95	4.01	V
Over Voltage Protection		$V_{FB(OVP)}$		6.4	8	9.6	V

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Typical Performance Characteristics



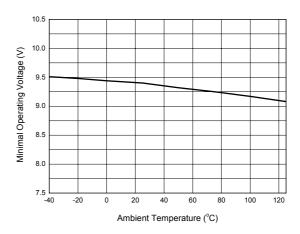
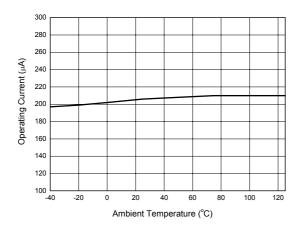


Figure 4. Start-up Voltage vs. Ambient Temperature

Figure 5. Mininal Operating Voltage vs. Ambient Temperature



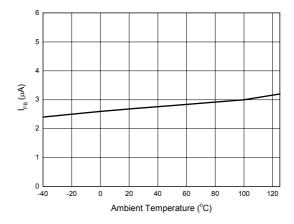


Figure 6. Operating Current vs. Ambient Temperature

Figure 7. I_{FB} vs. Ambient Temperature



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Typical Application

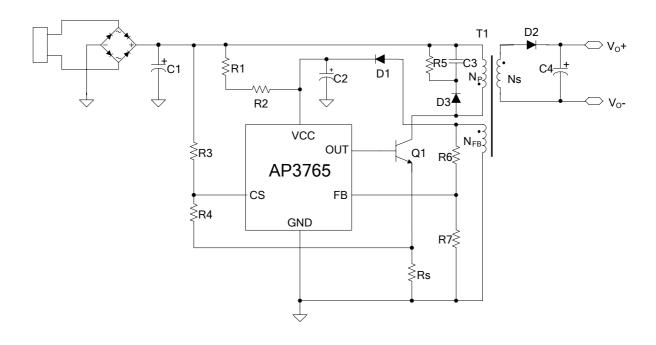


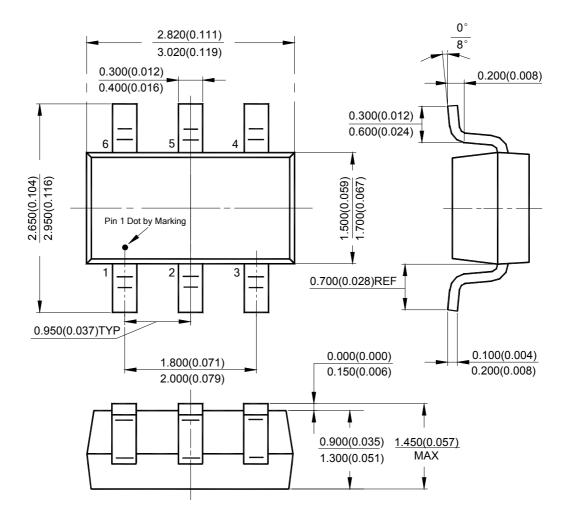
Figure 8. 5V/700mA Output for Battery Charger of Mobile Phone



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Mechanical Dimensions

SOT-23-6 Unit: mm(inch)







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